SLLS038B - OCTOBER 1980 - REVISED MAY 1995

- Meets or Exceeds the Requirements of ANSI Standards EIA/TIA-422-B and RS-485 and ITU Recommendation V.11
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- 3-State Outputs
- Common-Mode Output Voltage Range of -7 V to 12 V
- Active-High and Active-Low Enables
- Thermal Shutdown Protection
- Positive- and Negative-Current Limiting
- Operates From Single 5-V Supply
- Logically Interchangeable With AM26LS31

description

The SN75172 is a monolithic quadruple differential line driver with 3-state outputs. It is designed to meet the requirements of ANSI Standards EIA/TIA-422-B and RS-485 and ITU Recommendation V.11. The device is optimized for balanced multipoint bus transmission at rates of up to 4 megabaud. Each driver features wide positive and negative common-mode output voltage ranges, making it suitable for party-line applications in noisy environments.

N PACKAGE (TOP VIEW)								
1A [1Y [1Z [2Z [2Y [GND]		16] V _{CC} 15] 4A 14] 4Y 13] 4Z 12] G 11] 3Z 10] 3Y 9] 3A						
	W PAG (TOP \	CKAGE /IEW)						
1Z [1 2 3 4 5 6 7 8 9 10	20] V _{CC} 19] 4A 18] 4Y 17] NC 16] 4Z 15] G 14] 3Z 13] NC 12] 3Y 11] 3A						

NC - No internal connection

The SN75172 provides positive- and negative-current limiting and thermal shutdown for protection from line fault conditions on the transmission bus line. Shutdown occurs at a junction temperature of approximately 150°C. This device offers optimum performance when used with the SN75173 or SN75175 quadruple differential line receivers.

The SN75172 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each driver)								
INPUT	ENA	BLES	Ουτι	PUTS				
Α	G	G	Y	Z				
Н	Н	Х	н	L				
L	н	Х	L	Н				
н	Х	L	н	L				
L	Х	L	L	Н				
Х	L	Н	Z	Z				

H = high level, L = low level, X = irrelevant, Z = high impedance (off)



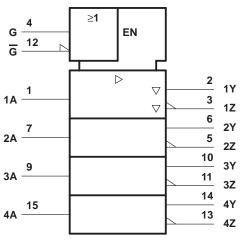
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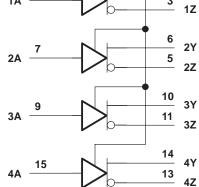
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logic symbol[†]



G 12 G 2 1Y 3

logic diagram (positive logic)



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Terminal numbers shown are for the N package.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)[‡]

Supply voltage, V _{CC} (see Note 1)	
Voltage range at any bus terminal	–10 V to 15 V
Input voltage, V _I	5.5 V
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. NOTE 1: All voltage values are with respect to the network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING
DW	1125 mW	9.0 mW/°C	720 mW
Ν	1150 mW	9.2 mW/°C	736 mW



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recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.75	5	5.25	V
High-level input voltage, VIH	2			V
Low-level input voltage, VIL			0.8	V
Common-mode output voltage, VOC		_	7 to 12	V
High-level output current, I _{OH}			-60	mA
Low-level output current, IOL			60	mA
Operating free-air temperature, T _A	0		70	°C

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT	
VIK	Input clamp voltage	lj = - 18 mA					-1.5	V
Vo	Output voltage	I ^O = 0			0		6	V
VOH	High-level output voltage	V _{IH} = 2 V,	V _{IL} = 0.8 V,	I _{OH} = -33 mA		3.7		V
VOL	Low-level output voltage	V _{IH} = 2 V,	V _{IL} = 0.8 V,	I _{OH} = 33 mA		1.1		V
IVOD1	Differential output voltage	I _O = 0			1.5		6	V
VOD2	Differential output voltage	R _L = 100 Ω,	See Figure 1		1/2 V _{OD1} or 2‡			V
		R _L = 54 Ω,	See Figure 1		1.5	2.5	5	V
V _{OD3}	Differential output voltage	See Note 2			1.5		5	V
$\Delta V_{OD} $	Change in magnitude of differential output voltage§						±0.2	V
Voc	Common-mode output voltage¶	$R_L = 54 \Omega \text{ or}$	100 Ω,	See Figure 1			+3 – 1	V
∆ VOC	Change in magnitude of common-mode output voltage§						±0.2	V
lo	Output current with power off	$V_{CC} = 0,$	$V_{O} = -7$ V to 12 V				±100	μΑ
I _{OZ}	High-impedance-state output current	$V_{O} = -7 V$ to	12 V				±100	μΑ
Iн	High-level input current	V _I = 2.7 V					20	μΑ
۱ _{IL}	Low-level input current	V _I = 0.5 V					-360	μΑ
		V _O = - 7 V				-180		
los	Short-circuit output current	VO = VCC					180	mA
		V _O = 12 V					500	
1	Supply ourrept (all drivers)	No load	Outputs enabled			38	60	mA
ICC	Supply current (all drivers)	NO IDad	Outputs disabled			18	40	mA

[†] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$. [‡] The minimum V_{OD2} with a 100- Ω load is either 1/2 V_{OD1} or 2 V, whichever is greater. [§] $\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level.

In ANSI Standard EIA/TIA-422-B, VOC, which is the average of the two output voltages with respect to ground, is called output offset voltage, VOS.

NOTE 2: See Figure 3-5 of EIA Standard RS-485.



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SYMBOL EQUIVALENTS							
DATA SHEET PARAMETER	EIA/TIA-422-B	RS-485					
VO	V _{oa,} V _{ob}	V _{oa,} V _{ob}					
IVOD1	Vo	Vo					
IVOD2	V _t (R _L = 100 Ω)	$V_t (R_L = 54 \Omega)$					
IVod2I		V _t (Test Termination) Measurement 2)					
	$ V_t - \overline{V}_t $	$ V_t - \overline{V}_t $					
V _{OC}	V _{os}	V _{os}					
	V _{os} – V _{os}	$ V_{OS} - \overline{V}_{OS} $					
IOS	I _{sa} , I _{sb}						
lo	I _{xa} , I _{xb}	l _{ia} ,l _{ib}					

switching characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
td(OD)	Differential-output delay time	R _I = 54 Ω,	See Figure 2		45	65	ns
tt(OD)	Differential-output transition time	$K_{L} = 54.52,$	See Figure 2		80	120	ns
^t PZH	Output enable time to high level	RL = 110 Ω,	See Figure 3		80	120	ns
tPZL	Output enable time to low level	RL = 110 Ω,	See Figure 4		45	80	ns
^t PHZ	Output disable time from high level	RL = 110 Ω,	See Figure 3		78	115	ns
^t PLZ	Output disable time from low level	R _L = 110 Ω,	See Figure 4		18	30	ns

PARAMETER MEASUREMENT INFORMATION

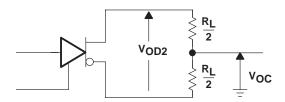
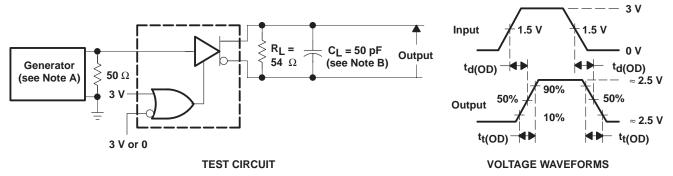


Figure 1. Differential and Common-Mode Output Voltages



NOTES: A. The input pulse is supplied by a generator having the following characteristics: $t_f \le 5$ ns, $t_f \le 5$ ns, PRR ≤ 1 MHz, duty cycle = 50%, $Z_O = 50 \Omega$.

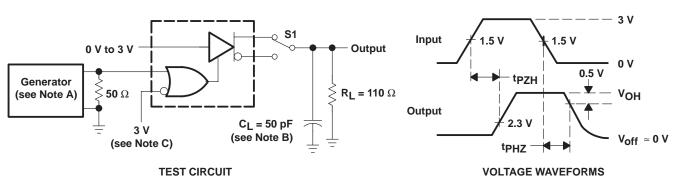
B. C_{L} includes probe and stray capacitance.

Figure 2. Differential-Output Test Clrcuit and Voltage Waveforms



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PARAMETER MEASUREMENT INFORMATION



- NOTES. A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, t_f \leq 5 ns, t_f \leq 5 ns, Z_O = 50 Ω .
 - B. CL includes probe and stray capacitance.
 - C. To test the active-low enable G, ground G and apply an inverted waveform to G.

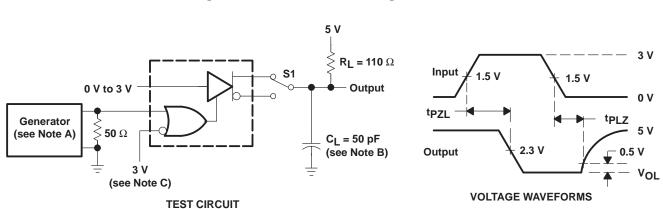


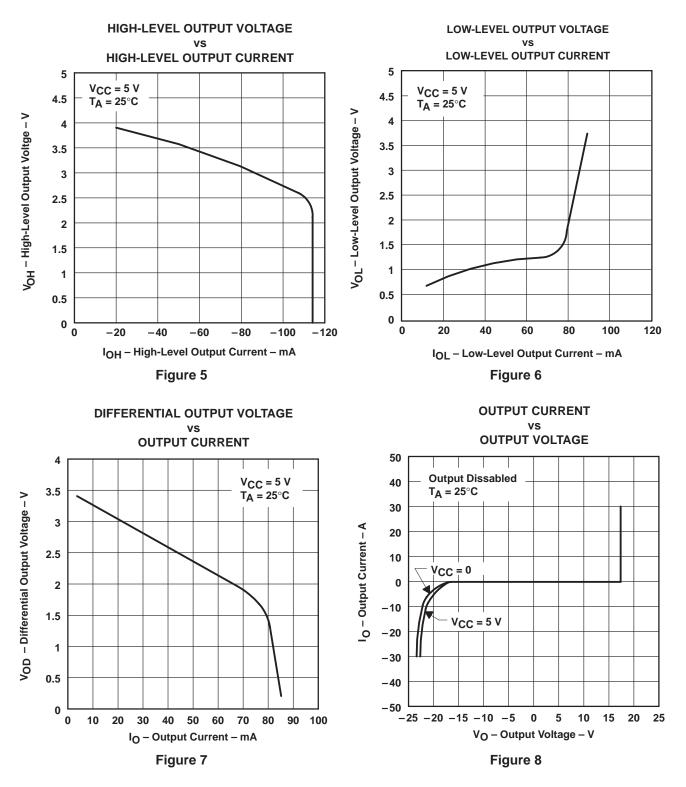
Figure 3. Test Circuit and Voltage Waveforms

- NOTES. A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, duty cycle = 50%, t_f \leq 5 ns, t
 - B. CL includes probe and stray capacitance.
 - C. To test the active-low enable \overline{G} , ground G and apply an inverted waveform to \overline{G} .

Figure 4. Test Circuit and Voltage Waveforms

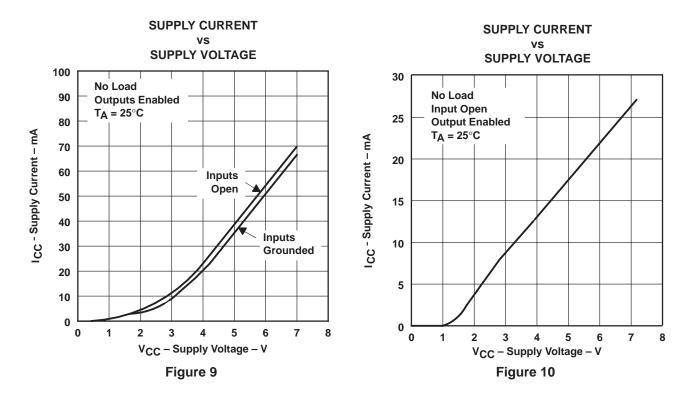


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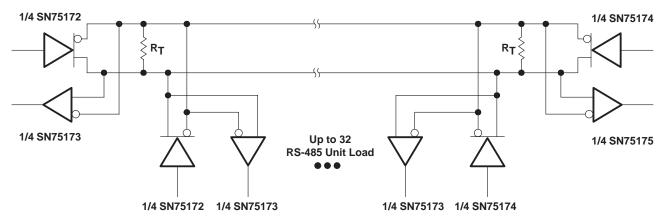


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TYPICAL CHARACTERISTICS

APPLICATION INFORMATION



NOTE A: The line length should be terminated at both ends in its characteristic impedance (R_T = Z_O). Stub lengths off the main line should be kept as short as possible.

Figure 11





11-Apr-2013

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
SN75172DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75172	Samples
SN75172DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75172	Samples
SN75172DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75172	Samples
SN75172DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75172	Samples
SN75172DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75172	Samples
SN75172DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75172	Samples
SN75172N	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75172N	Samples
SN75172NE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75172N	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



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PACKAGE OPTION ADDENDUM

11-Apr-2013

⁽⁴⁾ Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75172DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN75172DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

31-Jan-2014



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75172DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN75172DWR	SOIC	DW	20	2000	367.0	367.0	45.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



LAND PATTERN DATA



NOTES:

A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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